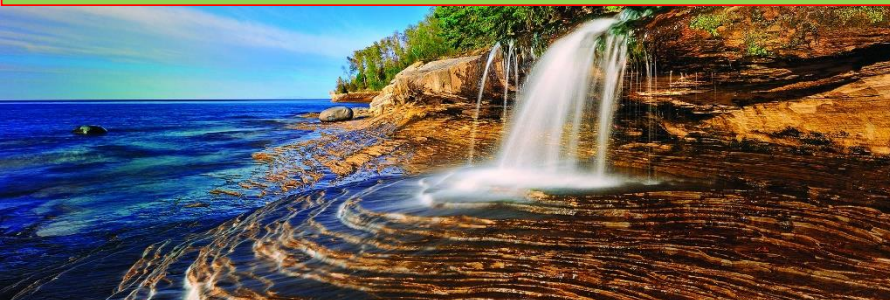


IEEE MWSCAS 2021

2021 IEEE 64th International Midwest Symposium on Circuits and Systems, Lansing, Michigan, USA | Aug. 9-11, 2021. <http://www.mwscas2021.org>



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The IEEE International Midwest Symposium on Circuits and Systems

(MWSCAS) is the oldest, and now the flagship, Circuits and Systems symposium.

The 64th meeting of the MWSCAS is planned to be in Lansing, Michigan, USA, from Aug 8-11, 2021. The MWSCAS 2021 will be ready to pivot to virtual symposium if necessary. It will include oral and poster sessions, a student paper contest, keynote addresses, regular and special sessions, and tutorials presented by world experts in wide range of circuits and systems topics. *The 2021 Symposium theme is artificial intelligence (AI) and autonomous circuits and systems, and hopes to bring forward solutions to consequences of the COVID-19, from detection, testing to predictions.* Topics include, but are not limited to:

- COVID-19 detection, testing, prediction
- Autonomous & Intelligent Circuits/Systems
- Deep Neural Networks and Reinforcement Learning
- Machine Learning and Artificial Intelligence
- Neuromorphic Circuits and Systems
- Analog and Mixed Signal Integrated Circuits
- Digital Integrated Circuits, SOC, and NOC
- Digital Signal Processing
- IoTs and wearables
- Bioengineering Systems and Bio Chips
- Bio-inspired Green Technologies
- Trusted Electronics and Security
- Communication Circuits and Systems
- Wireless Sensors and Systems
- Cloud & System Architectures
- Embedded Electronics
- Image Processing and Multimedia Systems
- Nanoelectronics and Nanotechnology
- MEMS/NEMS
- RFICs, Microwave, and Optical Systems
- Power Management, Energy Harvesting, and Wireless Power
- Hardware/Software Co-design & Verification
- Power Systems and Power Electronics
- Novel Linear/Non-linear Circuits and Systems

Prospective authors are invited to submit a full paper (4 pages) describing original work through the on-line submission system for the conference through a link on the MWSCAS 2021 conference website. Papers should follow the formatting instructions given in the author's kit on the website.

Papers will be accepted for either lecture or poster presentation. Review criteria for both lecture and poster presentation formats are identical; the presentation format will be chosen to facilitate topical session grouping and time constraints. Students are encouraged to participate in the Best Student Paper Award contest. Submissions of demos and proposals for tutorials and special sessions are also solicited. Accepted papers will be published in the MWSCAS 2021 Proceedings subject to advance registration of at least one of the authors at the author rate. All papers published in the MWSCAS 2021 Proceedings will be submitted for inclusion into **IEEEXplore**.

The Greater Lansing Area in Michigan includes the Michigan Capital (Lansing) and is home to Michigan State University and a host of diverse industries, from automotive, communication, medical small tech companies. Michigan has several international Universities. Michigan, the home to the three lakes, has numerous natural sights for touring including islands and the beautiful "upper" peninsula.

Important Dates (submission deadlines)

March 1, 2021

March 8, 2021

April 5, 2021

April 26, 2021

May 17, 2021

Special Session Proposals

Regular Papers

Tutorial Session Proposals

Notice of Paper Acceptance

Camera-Ready Paper Due